

G

F

E

D

C

B

A

RoHS

Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)

SPECIFICATIONS
Rated Current:1.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:500V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:-40°c to +105°c

Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V-0)
Standard: PA9T
Max.Processing Temp: 230°C for 30-60 seconds
(260°C for 10 seconds)

Ordering Information

HC-BH730 XX M XX X B K00 X 0X(1,2)

No.of Pins 10-100P

Contact Plating G0:Gold Flash G2:5U" Gold G3:10U" Gold G4:15U" Gold G5:30U" Gold S0:Gold Flash/Tin SN:Tin

Insulator Material Option A=BK-PBT B=BK-PA66 C=BK-PA6T D=BK-PA46 E=BK-PA9T F=BK-LCP

Packing O=PE Bag A=Troy T=Tube P=Tube+Cap R=Reel+Cap M=Reel+Mylar

				OPERATION		DRAW	Ayang		SCALE	FIT	HECON 东莞市禾康电子有限公司 DONGGUAN HECON ELECTRONICS CO.,LTD	
				X.X	±0.30					UNIT		
				X.XX	±0.20	CHECK			SIZE	A4	PART NO. HC-BH730XXMXXBK00X0X(1,2)	
				X.XXX	±0.10				SHEET	1/1		
A0		NEW DRAWING		Angle	±3'	APPROVE			PROJ.	◆ ▢ ▣ ▤ ▥ ▦ ▧ ▨ ▩	TITLE:	1.27mm H4.9 SMT Npin L=7.0 Box Header
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	DIM	TOL							

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No. of Pins
10-100P

Contact	Plating
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G2:5U"	Gold
G3:10U"	Gold
G4:15U"	Gold
G5:30U"	Gold
S0:Gold	Flash/Tin
SN:Tin	

Insulator Material
Option
A=BK-PBT
B=BK-PA66
C=BK-PA6T
D=BK-PA46
E=BK-PA9T
F=BK-LCP

Packing
0=PE Bag
A=Tray
T=Tube
P=Tube+Cap
R=Reel+Cap
M=Reel+Mylar

TYPE2 With Post

TYPE1 Without Post

				OPERATION		DRAW	Ayang		SCALE	FIT	HECON 东莞市禾康电子有限公司 DONGGUAN HECON ELECTRONICS CO.,LTD	
				X.X	±0.30				CHECK			
				X.XX	±0.20	APPROVE					SIZE	A4
A0		NEW DRAWING		X.XXX	±0.10							SHEET
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle	±3°							PROJ.
				DIM	TOL							